

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) The combination of a semiconductor substrate singulation saw and a chuck for holding a substrate comprising:
a support having an extension arm connected thereto;
a saw attached to the extension arm of the support, the saw having at least two blades connected thereto supported above a table by the support and oriented to cut mutually parallel paths in a surface of a semiconductor substrate positioned on the table, at least one of the saw blades horizontally translatable on said support and the other saw blade having a fixed horizontal position on said support; and
a chuck having at least one cutting pedestal located thereon mounted on the table, the chuck for holding the substrate during cutting thereof by the saw, the chuck translatable in a horizontal direction and a transverse direction in relation to the saw .
2. (Previously Presented) The combination of claim 1, wherein the chuck further comprises:
a chuck table; and
a plurality of cutting pedestals, each cutting pedestal being mounted on the chuck table.
3. (Previously Presented) The combination of claim 2, wherein the chuck further comprises:
at least one clamp pedestal; and
at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.
4. (Previously Presented) The combination of claim 3, wherein the chuck further comprises:
at least one alignment apparatus having a portion attached to the chuck table.

5. (Previously Presented) The combination of claim 4, wherein the at least one alignment apparatus comprises:

at least one alignment pin having a portion for engaging a portion of the substrate.

6. (Previously Presented) The combination of claim 4, wherein the at least one alignment apparatus comprises:

an aperture in the chuck table for receiving the substrate therein.

7. (Previously Presented) The combination of claim 4, wherein the at least one alignment apparatus comprises:

a pair of alignment pins, each alignment pin having a portion thereof attached to the chuck table and a portion thereof for engaging a portion of the substrate.

8. (Canceled)

9. (Previously Presented) The combination of claim 1, wherein at least one of the at least two blades is laterally translatable relative to another of the at least two blades.

10. (Previously Presented) The combination of claim 9, wherein the at least one of the at least two blades is raisable relative to the another of the at least two blades.

11. (Canceled)

12. (Previously Presented) The combination of claim 1, wherein the at least two blades are translatable in at least one direction relative to the table.

13. (Withdrawn) A combination of a semiconductor substrate singulation saw and a table for mounting a substrate comprising:

a saw having at least two blades supported above a table and oriented to cut mutually parallel paths in a surface of a semiconductor substrate positioned on the table; and a chuck having at least one cutting pedestal located thereon mounted on the table, the chuck for holding the substrate during cutting thereof by the saw.

14. (Withdrawn) The combination of claim 13, wherein the chuck further comprises:
a chuck table; and
a plurality of cutting pedestals, each cutting pedestal being mounted on the chuck table.

15. (Withdrawn) The combination of claim 14, wherein the chuck further comprises:
at least one clamp pedestal; and
at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.

16. (Withdrawn) The combination of claim 15, wherein the chuck further comprises:
at least one alignment apparatus having a portion thereof attached to the chuck table.

17. (Withdrawn) The combination of claim 16, wherein the at least one alignment apparatus comprises:
at least one alignment pin having a portion for engaging a portion of the substrate.

18. (Withdrawn) The combination of claim 16, wherein the at least one alignment apparatus comprises:
an aperture in the chuck table for receiving the substrate therein.

19. (Withdrawn) The combination of claim 16, wherein the at least one alignment apparatus comprises:
a pair of alignment pins, each alignment pin having a portion thereof attached to the chuck table and a portion thereof for engaging a portion of the substrate.

20. (Withdrawn) The combination of claim 13, wherein the saw further comprises:
at least two blades for sawing the substrate.

21. (Withdrawn) The combination of claim 20, wherein at least one of the at least
two blades is laterally translatable relative to another of the at least two blades.

22. (Withdrawn) The combination of claim 21, wherein the at least one of the at least
two blades is raisable relative to the another of the at least two blades.

23. (Withdrawn) The combination of claim 20, wherein the table is translatable in at
least one direction relative to the at least two blades.

24. (Withdrawn) The combination of claim 20, wherein the at least two blades are
translatable in at least one direction relative to the table.

25. (Withdrawn) A chuck used in semiconductor substrate singulation for holding a
substrate to be singulated by a saw having a table comprising:
a chuck having at least one cutting pedestal located thereon mounted on the table, the chuck for
holding the substrate during cutting thereof by the saw.

26. (Withdrawn) The chuck of claim 25, further comprising:
a plurality of cutting pedestals, each cutting pedestal being mounted on the table.

27. (Withdrawn) The chuck of claim 26, further comprising:
at least one clamp pedestal; and
at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.

28. (Withdrawn) The chuck of claim 27, further comprising:
at least one alignment apparatus having a portion attached to the table.

29. (Withdrawn) The chuck of claim 28, wherein the at least one alignment apparatus comprises:

at least one alignment pin having a portion for engaging a portion of the substrate.

30. (Withdrawn) The chuck of claim 28, wherein the at least one alignment apparatus comprises:

an aperture in the table for receiving the substrate therein.

31. (Withdrawn) The chuck of claim 28, wherein the at least one alignment apparatus comprises:

a pair of alignment pins, each alignment pin having a portion thereof attached to the table and a portion thereof for engaging a portion of the substrate.